

Device Material Content

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Package: 81 csfBGA
Total Device Weight 35.82 Milligrams (mg)

Package Code:

MG81

Products:

LIF-MD6000

Assembly: ASET
Size (mm): 4.5 x 4.5
Lead pitch (mm): 0.5
MSL: 3
Reflow max (°C): 260

April, 2018

	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	14.59%	5.225	14.59%	5.225	Silicon chip	7440-21-3	100.00%	Die size: 2.0 x 2.0 x 0.177mm
Mold Compound	49.52%	17.737	3.06%	1.0961	Epoxy resins	-	6.18%	Sumitomo EME-G311SA Type C
			2.80%	1.0039	Phenol resins	-	5.66%	
			1.40%	0.5020	Metal Hydroxide	-	2.83%	
			2.57%	0.9206	Carbon Black	1333-86-4	5.19%	
			32.69%	11.7082	Silica fused	60676-86-0	66.01%	
			7.00%	2.5080	Silica fused	7631-86-9	14.14%	
Substrate	18.44%	6.605	0.44%	0.1570	Barium Sulfate	7727-43-7	2.38%	PFR800 Aus410
			0.14%	0.0496	Talc	14807-96-6	0.75%	
			0.14%	0.0496	Phosphinooxide derivative	-	0.75%	
			0.09%	0.0331	Silica	-	0.50%	
			0.35%	0.1237	Epoxy Resin	-	1.87%	
			3.33%	1.1924	Thermosetting resin	-	18.05%	
			3.33%	1.1924	Continuous Filament Glass	-	18.05%	
			10.62%	3.8050	Copper	7440-50-8	57.61%	
			0.01%	0.0023	OSP	-	0.03%	
Repassivation polyimide	0.07%	0.024	0.037%	0.0132	N-Methyl-2-pyrrolidone	872-50-4	55.00%	
			0.003%	0.0012	Proprietary Monomer	-	5.0%	
			0.000%	0.0001	Methanol	67-56-1	0.50%	
			0.026%	0.0095	Non regulated ingredients	-	39.50%	
UBM	0.04%	0.016	0.009%	0.0032	Titanium (Ti)	7440-32-6	20.25%	
			0.036%	0.0128	Copper (Cu)	7440-50-8	79.75%	
Bump	3.81%	1.363	3.072%	1.1002	Tin (Sn)	7440-31-5	80.72%	
			0.056%	0.0202	Silver (Ag)	7440-22-4	1.48%	
			0.537%	0.1922	Nickel (Ni)	7440-02-0	14.10%	
			0.141%	0.0506	Copper (Cu)	7440-50-8	3.71%	
Solder Balls	13.54%	4.851	13.306%	4.7661	Tin (Sn)	7440-31-5	98.25%	Sn0.9825Ag1.2Cu0.5Ni0.05
			0.163%	0.0582	Silver (Ag)	7440-22-4	1.20%	
			0.068%	0.0243	Copper (Cu)	7440-50-8	0.50%	
			0.007%	0.0024	Nickel (Ni)	7440-02-0	0.05%	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible. Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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